

▶ **SIMMP-00XXB033-G** Micro SIM card Conn. SMT, 8 Circuits

Product Name : Micro SIM card Conn. SMT, 8 Circuits

Part No : SIMMP-00X XXB033-G

(1) (2)

(1) pin no.

6 : 6pin

8 : 8pin

(2) Plating:

01 : Gold Flash



APPLICATION:

1. For SIM - Smart Card Use.

Termination Interface: Surface mount

Ports: 1

Durability: 5,000 min

SPECIFICATION:

1. Contact resistance:
Contact: 50 mΩ typical, 100 mΩ Max.
2. Insulation resistance: >1000 megaohms / 500 VDC
3. Operating temperature: -40°C ~ 85°C
4. Operating Humidity: 10%~95%RH
5. Solderability:
Vapor phase: 215°C, 30sec. MAX
IR reflow: 250°C, 10sec. MAX
Manual soldering: 370°C, 3sec. MAX

MATERIAL and FINISH:

1. Insulation material : High Temperature Plastic (UL 94V-0)
2. Contact material : Copper Alloy
3. Finish: Gold plating on contact area
4. Slide: Thermoplastic, UL 94-V0

Net Weight: 0.5g

Packing:

1. Tape on reel: 900pcs/reel; 10reels/carton